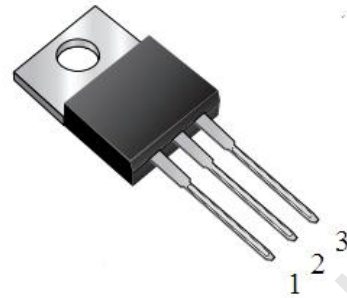
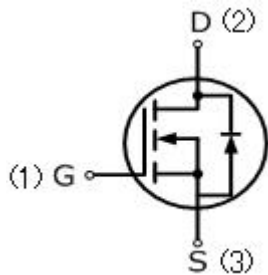


FEATURE

- 20A,60V,RDS(ON)=36m Ω @VGS
- =10V/10A Low gate charge
- Low Ciss
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



TO-220AB

Absolute Maximum Ratings($T_C=25^{\circ}\text{C}$, unless otherwise noted)				
Parameter		Symbol	IRF9Z24NPBF	UNIT
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current		I_D	20	A
Pulsed Drain Current(Note1)		I_{DM}	80	
Single Pulse Avalanche Energy (Note 2)		E_{AS}	155	mJ
Avalanche Current(Note1)		I_{AR}	20	A
Repetitive Avalanche Energy (Note1)		E_{AR}	5.3	mJ
Reverse Diode dV/dt (Note 3)		dv/dt	7.0	V/ns
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 to +150	$^{\circ}\text{C}$
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		T_L	260	$^{\circ}\text{C}$
Mounting Torque	6-32 or M3 screw		10	lbf • in
			1.1	N • m

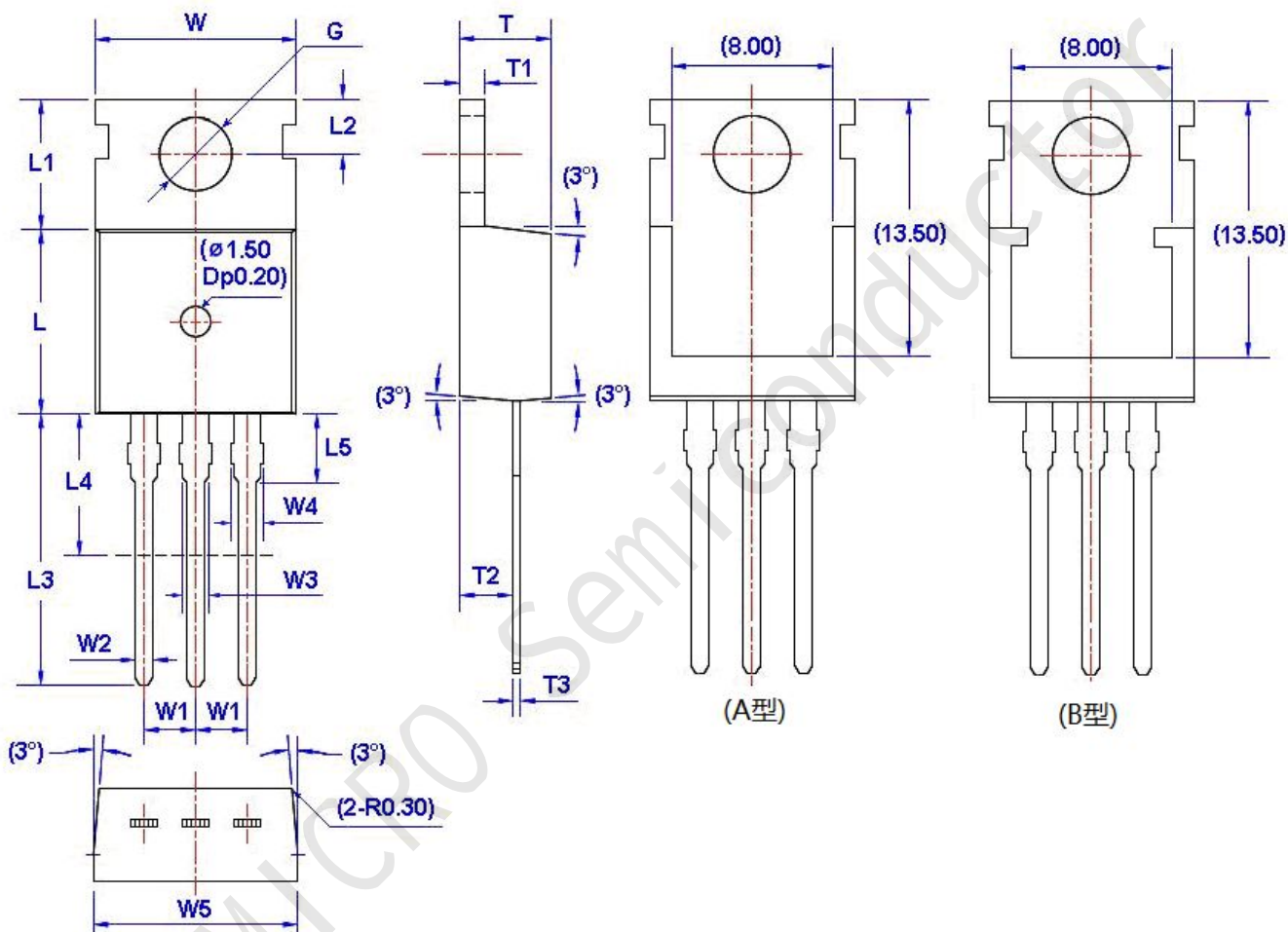
Electrical Characteristics (T _c =25℃,unless otherwise noted)						
Parameter	Symbol	Test Conditions	Mix	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V,I _D =250uA	60	—	—	V
Breakdown Temperature Coefficient	ΔBV _{DSS} /ΔT _J	Reference to 25℃ , I _D =250uA	—	0.5	—	V/℃
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	—	—	1	uA
Gate-Body Leakage Current,Forward	I _{GSSF}	V _{GS} =20V,V _{DS} =0V	—	—	100	nA
Gate-Body Leakage Current,Reverse	I _{GSSR}	V _{GS} =-20V,V _{DS} =0V	—	—	-100	nA
On Characteristics						
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =10V,I _D =250uA	1.0	—	3.0	V
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V,I _D =10A	—	—	36	m Ω
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =25V,V _{GS} =0V, f=1.0MHZ	—	450	590	pF
Output Capacitance	C _{oss}		—	170	220	pF
Reverse Transfer Capacitance	C _{rss}		—	25	35	pF
Switching Characteristics						
Turn-On Delay Time	t _{d(on)}	V _{DD} =30V,I _D =10A, R _G =25Ω (Note4,5)	—	5	20	ns
Turn-On Rise Time	t _r		—	45	100	ns
Turn-Off Delay Time	t _{d(off)}		—	20	50	ns
Turn-Off Fall Time	t _f		—	25	60	ns
Total Gate Charge	Q _g	V _{DS} =48V,I _D =20A, V _{GS} =10V, (Note4,5)	—	11.5	15	nC
Gate-Source Charge	Q _{gs}		—	3	—	nC
Gate-Drain Charge	Q _{gd}		—	4.5	—	nC
Drain-Source Body Diode Charcteristics and Maximum Ratings						
Continuous Diode Forward Current	I _S		—	—	20	A
Pulsed Diode Forward Current	I _{SM}		—	—	80	A
Diode Forward Voltage	V _{SD}	I _S =20A,V _{GS} =0V	—	—	1.5	V
Reverse Recovery Time	t _{rr}	V _{GS} =0V,I _S =20A,	—	43	—	ns
Reverse Recovery Charge	Q _{rr}	dI _F /dt=100A/us, (Note4)	—	50	—	uC

Notes

1. Repetitive Rating; pulse width limited by maximum junction temperature.
2. $V_{DD}=10V, L=1mH, R_g=25\Omega, I_{AS}=20A, T_J=25^{\circ}\text{C}$.
3. $I_{SD} \leq I_D, dI/dt=200A/\mu s, V_{DD} \leq BV_{DSS}$, starting $T_J=25^{\circ}\text{C}$.
4. Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.
5. Repetitive rating; pulse width limited by maximum junction temperature.

TO-220AB

Unit: mm



Symbol	Size		Symbol	Size		Symbol	Size		Symbol	Size	
	Min	Max		Min	Max		Min	Max		Min	Max
W	9.66	10.28	W5	9.80	10.20	L4**	6.20	6.60	T3	0.45	0.60
W1	2.54 (TYP)		L	9.00	9.40	L5	2.79	3.30	G(Φ)	3.50	3.70
W2	0.70	0.95	L1	6.40	6.80	T	4.30	4.70			
W3	1.17	1.37	L2	2.70	2.90	T1	1.15	1.40			
W4*	1.32	1.72	L3	12.70	14.27	T2	2.20	2.60			